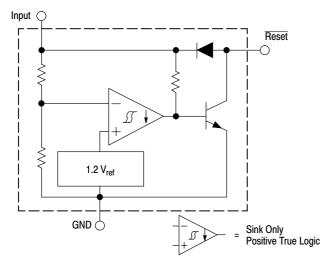
Undervoltage Sensing Circuit

The MC34064 is an undervoltage sensing circuit specifically designed for use as a reset controller in microprocessor–based systems. It offers the designer an economical solution for low voltage detection with a single external resistor. The MC34064 features a trimmed–in–package bandgap reference, and a comparator with precise thresholds and built-in hysteresis to prevent erratic reset operation. The open collector reset output is capable of sinking in excess of 10 mA, and operation is guaranteed down to 1.0 V input with low standby current. The MC devices are packaged in 3–pin TO-92, micro size TSOP–5, 8–pin SOIC–8 and Micro8TM surface mount packages. The NCV device is packaged in SOIC–8 and TO–92.

Applications include direct monitoring of the 5.0 V MPU/logic power supply used in appliance, automotive, consumer and industrial equipment.

Features

- Trimmed-In-Package Temperature Compensated Reference
- Comparator Threshold of 4.6 V at 25°C
- Precise Comparator Thresholds Guaranteed Over Temperature
- Comparator Hysteresis Prevents Erratic Reset
- Reset Output Capable of Sinking in Excess of 10 mA
- Internal Clamp Diode for Discharging Delay Capacitor
- Guaranteed Reset Operation with 1.0 V Input
- Low Standby Current
- Economical TO-92, TSOP-5, SOIC-8 and Micro8 Surface Mount Packages
- NCV Prefix for Automotive and Other Applications Requiring Site and Control Changes
- Pb–Free Packages are Available

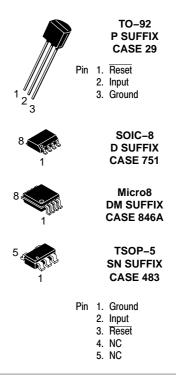


This device contains 21 active transistors. Figure 1. Representative Block Diagram

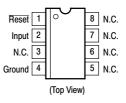


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PIN CONNECTIONS



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 7 of this data sheet.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Power Input Supply Voltage	V _{in}	-1.0 to 10	V
Reset Output Voltage	V _O	10	V
Reset Output Sink Current (Note 2)	I _{Sink}	Internally Limited	mA
Clamp Diode Forward Current, Reset to Input Pin (Note 2)	۱ _F	100	mA
Power Dissipation and Thermal Characteristics P Suffix, Plastic Package Maximum Power Dissipation @ $T_A = 25^{\circ}C$ Thermal Resistance, Junction-to-Air D Suffix, Plastic Package Maximum Power Dissipation @ $T_A = 25^{\circ}C$ Thermal Resistance, Junction-to-Air DM Suffix, Plastic Package Maximum Power Dissipation @ $T_A = 25^{\circ}C$ Thermal Resistance, Junction-to-Air	P _D R _{θJA} P _D R _{θJA} P _D R _{θJA}	625 200 625 200 520 240	mW °C/W °C/W °C/W mW °C/W
Operating Junction Temperature	TJ	+150	°C
Operating Ambient Temperature MC34064 MC33064 NCV33064	T _A	0 to +70 -40 to +85 -40 to +125	°C
Storage Temperature Range	T _{stg}	-65 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. ESD data available upon request.

ELECTRICAL CHARACTERISTICS (For typical values $T_A = 25^{\circ}$ C, for min/max values T_A is the operating ambient temperature range that applies [Notes 3 and 4] unless otherwise noted.)

Characteristics	Symbol	Min	Тур	Max	Unit
COMPARATOR	•	•		•	-
Threshold Voltage High State Output (V _{in} Increasing) Low State Output (V _{in} Decreasing) Hysteresis	V _{IH} VIL VH	4.5 4.5 0.01	4.61 4.59 0.02	4.7 4.7 0.05	V
RESET OUTPUT					
$\begin{array}{l} \text{Output Sink Saturation} \\ (\text{V}_{in} = 4.0 \text{ V}, \text{I}_{\text{Sink}} = 8.0 \text{ mA}) \\ (\text{V}_{in} = 4.0 \text{ V}, \text{I}_{\text{Sink}} = 2.0 \text{ mA}) \\ (\text{V}_{in} = 1.0 \text{ V}, \text{I}_{\text{Sink}} = 0.1 \text{ mA}) \end{array}$	V _{OL}	- - -	0.46 0.15 -	1.0 0.4 0.1	V
Output Sink Current (V _{in} , Reset = 4.0 V)	I _{Sink}	10	27	60	mA
Output Off-State Leakage (V _{in} , Reset = 5.0 V)	I _{ОН}	-	0.02	0.5	μΑ
Clamp Diode Forward Voltage, Reset to Input Pin ($I_F = 10 \text{ mA}$)	V _F	0.6	0.9	1.2	V
TOTAL DEVICE	-	-	-	-	-

Operating Input Voltage Range	V _{in}	1.0 to 6.5	_	-	V
Quiescent Input Current (V _{in} = 5.0 V)	l _{in}	-	390	500	μΑ

2. Maximum package power dissipation limits must be observed.

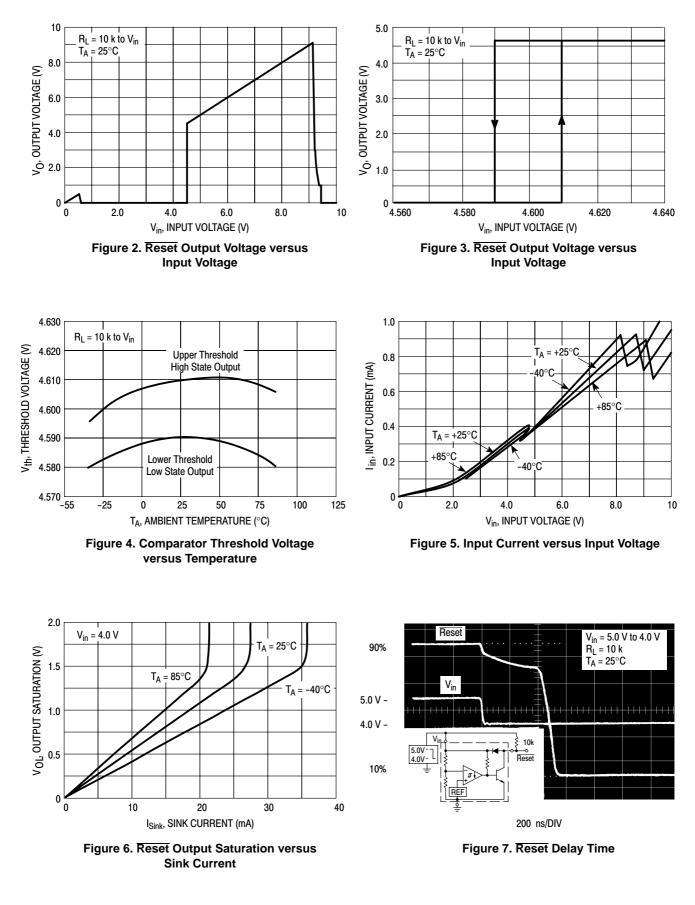
3. Low duty cycle pulse techniques are used during test to maintain junction temperature as close to ambient as possible.

4. $T_{low} = 0^{\circ}C$ for MC34064 $T_{high} = +70^{\circ}C$ for MC34064

-40°C for MC33064 +85°C for MC33064

-40°C for NCV33064 +125°C for NCV33064

5. NCV prefix is for automotive and other applications requiring site and change control.



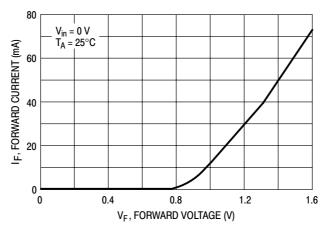


Figure 8. Clamp Diode Forward Current versus Voltage

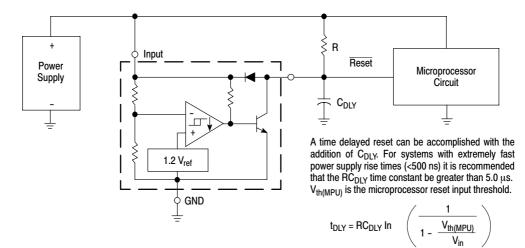
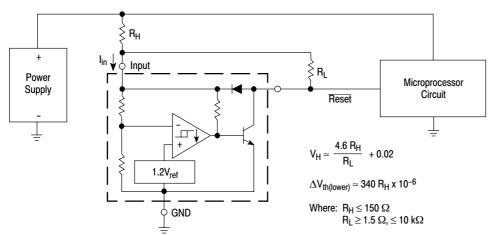


Figure 9. Low Voltage Microprocessor Reset

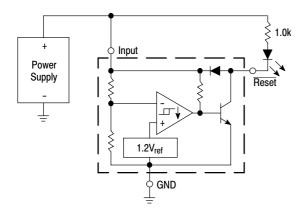


TEST DATA

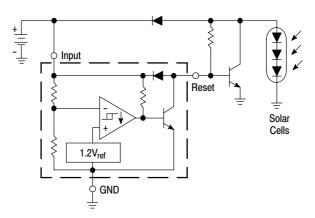
V _H (mV)	∆V _{th} (mV)	R _H (Ω)	R _L (kΩ)
20	0	0	0
51	3.4	10	1.5
40	6.8	20	4.7
81	6.8	20	1.5
71	10	30	2.7
112	10	30	1.5
100	16	47	2.7
164	16	47	1.5
190	34	100	2.7
327	34	100	1.5
276	51	150	2.7
480	51	150	1.5

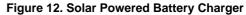
Comparator hysteresis can be increased with the addition of resistor R_H . The hysteresis equation has been simplified and does not account for the change of input current I_{in} as V_{CC} crosses the comparator threshold (Figure 4). An increase of the lower threshold $\Delta V_{th(lower)}$ will be observed due to I_{in} which is typically 340 μA at 4.59 V. The equations are accurate to $\pm 10\%$ with R_H less than 150 Ω and R_L between 1.5 $k\Omega$ and 10 $k\Omega$.

Figure 10. Low Voltage Microprocessor Reset with Additional Hysteresis









Results

35 mV

12 mV

77%

60 mVpp

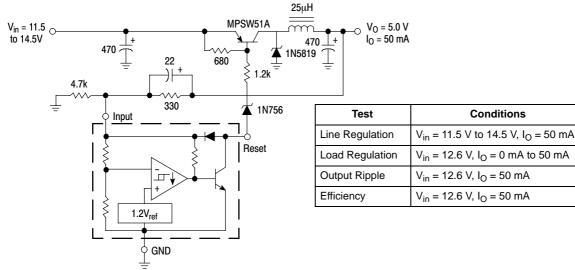
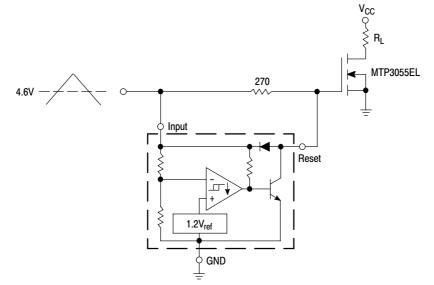


Figure 13. Low Power Switching Regulator



Overheating of the logic level power MOSFET due to insufficient gate voltage can be prevented with the above circuit. When the input signal is below the 4.6 V threshold of the MC34064, its output grounds the gate of the L² MOSFET.

Figure 14. MOSFET Low Voltage Gate Drive Protection

ORDERING INFORMATION

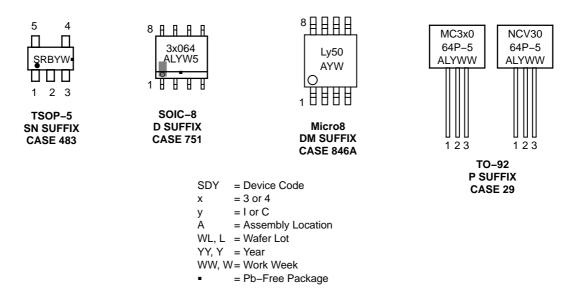
Device	Operating Temperature Range	Package	Shipping [†]
MC34064D-005		SOIC-8	
MC34064D-005G		SOIC-8 (Pb-Free)	98 Units / Rail
MC34064D-5R2		SOIC-8	
MC34064D-5R2G		SOIC-8 (Pb-Free)	2500 Units/ Tape & Reel
MC34064DM-5R2		Micro8	
MC34064DM-5R2G		Micro8 (Pb–Free)	4000 Units / Tape & Reel
MC34064P-005		TO-92	
MC34064P-005G	T 000 to 17000	TO-92 (Pb-Free)	2000 Units / Bag
MC34064P-5RA	$T_A = 0^{\circ}C$ to $+70^{\circ}C$	TO-92	
MC34064P-5RAG		TO-92 (Pb-Free)	2000 Units / Tape & Reel
MC34064P-5RP		TO-92	
MC34064P-5RPG		TO–92 (Pb–Free)	
MC34064P-5RM		TO-92	2000 Units / Ammo Pack
MC34064P-5RMG		TO–92 (Pb–Free)	
MC34064SN-5T1		TSOP-5	
MC34064SN-5T1G		TSOP–5 (Pb–Free)	3000 Units / Tape & Reel
MC33064D-005		SOIC-8	
MC33064D-005G		SOIC-8 (Pb-Free)	98 Units / Rail
MC33064D-5R2		SOIC-8	
MC33064D-5R2G		SOIC-8 (Pb-Free)	2500 Units / Tape & Reel
MC33064DM-5R2		Micro8	
MC33064DM-5R2G	T 4000 to 10500	Micro8 (Pb–Free)	4000 Units / Tape & Reel
MC33064P-005	$T_J = -40^{\circ}C \text{ to } +85^{\circ}C$	TO-92	
MC33064P-005G		TO-92 (Pb-Free)	2000 Units / Bag
MC33064P-5RA		TO-92	
MC33064P-5RAG		TO-92 (Pb-Free)	2000 Units / Tape & Reel
MC33064P-5RP		TO-92	
MC33064P-5RPG		TO-92 (Pb-Free)	2000 Units / Ammo Pack

ORDERING INFORMATION

Device	Operating Temperature Range	Package	Shipping [†]	
NCV33064D-5R2*		SOIC-8		
NCV33064D-5R2G*		SOIC-8 (Pb-Free)	2500 Units / Tape & Reel	
NCV33064P-5RA*		TO-92		
NCV33064P-5RAG*	T 4000 to 140500			2000 Units / Tape & Reel
NCV33064P-5RP*	$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$		0000 Heite / Assess Deale	
NCV33064P-5RPG*			2000 Units / Ammo Pack	
NCV33064DM-5R2*		Micro8		
NCV33064DM-5R2G*		Micro8 (Pb–Free)	4000 Units / Tape & Reel	

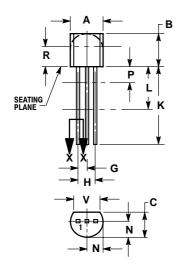
*NCV33064: T_{low} = -40°C, T_{high} = +125°C. Guaranteed by design. NCV prefix is for automotive and other applications requiring site and change control.

+For information on tape and reel specifications, including part orientation and tape sizes, pleaserefer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



MARKING DIAGRAMS

P SUFFIX PLASTIC PACKAGE CASE 29-11 (TO-92) ISSUE ÁL



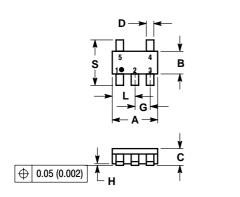


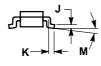
SECTION X-X

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED. 4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
Κ	0.500		12.70	
Г	0.250		6.35	
Ν	0.080	0.105	2.04	2.66
Ρ		0.100		2.54
R	0.115		2.93	
۷	0.135		3.43	

SN SUFFIX PLASTIC PACKAGE CASE 483-02 ISSUE D

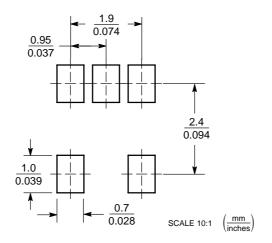




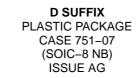
- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD 3.
- THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL. 4. A AND B DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE
- BURRS.

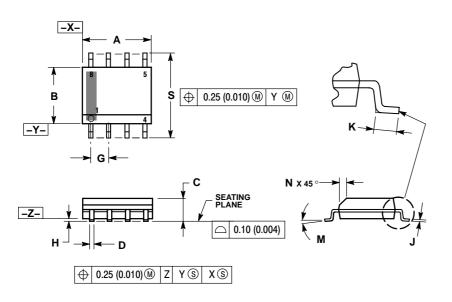
	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.1142	0.1220
в	1.30	1.70	0.0512	0.0669
С	0.90	1.10	0.0354	0.0433
D	0.25	0.50	0.0098	0.0197
G	0.85	1.05	0.0335	0.0413
н	0.013	0.100	0.0005	0.0040
J	0.10	0.26	0.0040	0.0102
Κ	0.20	0.60	0.0079	0.0236
L	1.25	1.55	0.0493	0.0610
м	0 °	10 °	0 °	10 °
S	2.50	3.00	0.0985	0.1181

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



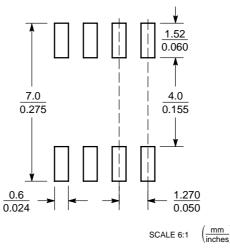


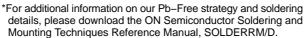
NOTES

- NOTES:
 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION
- MAXIMUM MATERIAL CONDITION. 6. 751–01 THRU 751–06 ARE OBSOLETE. NEW STANDARD IS 751-07.

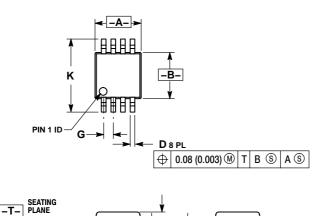
	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.80	5.00	0.189	0.197
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27	7 BSC	0.050 BSC	
н	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
ĸ	0.40	1.27	0.016	0.050
М	0 °	8 °	0 °	° 8
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

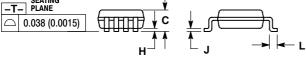
SOLDERING FOOTPRINT*







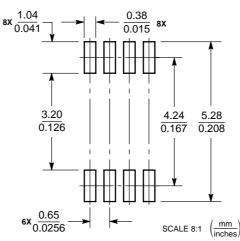




- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PDOTTIGLOUS OB CATE PURPORE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT
- EXCEED 0.15 (0.006) PER SIDE.
 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) DED OF PER SIDE.
- 5. 846A-01 OBSOLETE, NEW STANDARD 846A-02.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.114	0.122
В	2.90	3.10	0.114	0.122
С		1.10		0.043
D	0.25	0.40	0.010	0.016
G	0.65	BSC	0.026	BSC
Н	0.05	0.15	0.002	0.006
J	0.13	0.23	0.005	0.009
K	4.75	5.05	0.187	0.199
L	0.40	0.70	0.016	0.028

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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